

A

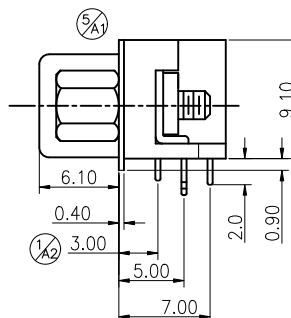
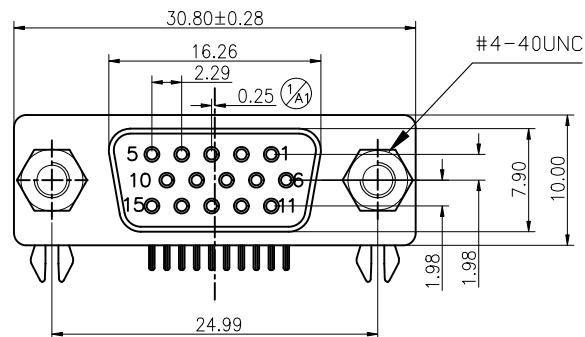
B

C

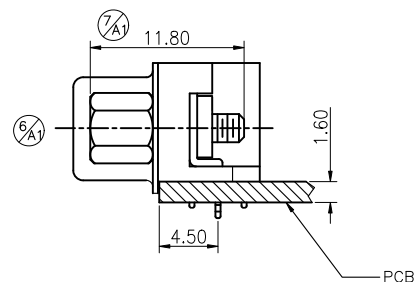
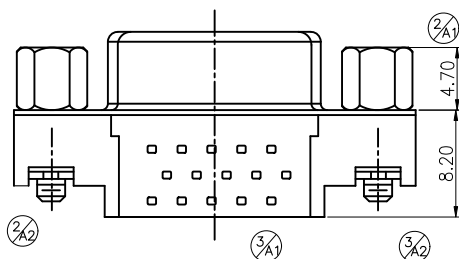
D

E

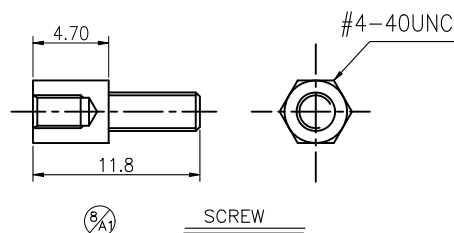
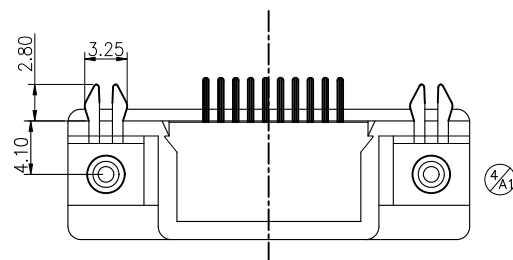
1



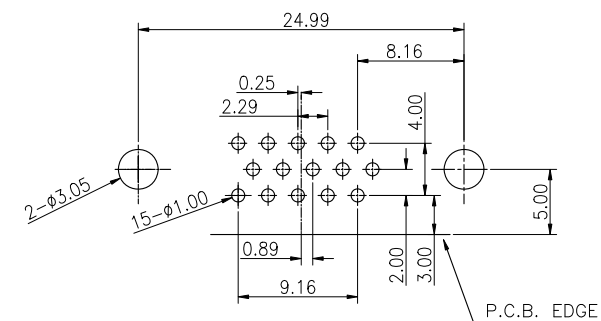
2



3



4



RECOMMENDED PCB LAYOUT(PCB THICKNESS: 1.6mm)
COMPONENT SIDE VIEW(TOLERANCE: ±0.05)

1.MATERIAL:

- 1.1 INSULATOR: PBT 30%GF , UL94V-0, COLOR: BLUE.
- 1.2 CONTACT: PHOSPHOR BRONZE.
- 1.3 SHELL: SPCC.
- 1.4 RIVET: COPPER ALLOY.
- 1.5 SCREW: SPCC.
- 1.6 FISH FORK: SPCC.

2.FINISH:

- 2.1 CONTACT: GOLD FLASH PLATED IN CONTACT AREA,
80u" Min. TIN PLATED IN SOLDER AREA,
30u" Min. NICKEL UNDERPLATED OVERALL.
- 2.2 FISH FORK: 80u" Min. TIN PLATED IN SOLDER AREA,
30u" Min. NICKEL UNDERPLATED OVERALL.
- 2.3 SHELL: 30u" MIN. NICKEL PLATED OVERALL.
- 2.4 RIVET: 30u" MIN. NICKEL PLATED OVERALL.
- 2.5 SCREW: 30u" MIN. NICKEL PLATED OVERALL.

3.ELECTRICAL CHARACTERISTICS:

- 3.1 CURRENT RATING: 5 A.
- 3.2 CONTACT RESISTANCE: 30mΩ MAX.
- 3.3 INSULATION RESISTANCE: 1000MΩ MIN .
- 3.4 OPERATING TEMPERATURE: -55°C ~ +105°C.

4.NOTES:

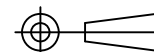
- 4.1 THIS COMPONENT AND ITS HOMOGENEOUS SUBCOMPONENTS ARE RoHS2.0 & REACH COMPLIANT.
- 4.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 5 SECONDS, AND ONLY FOR WAVE SOLDERING PROCESS.
- 4.3 SCREW RIGHT FORCE 0.2Nm~0.31Nm.

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REV.	DESCRIPTION	ECN NO.	NAME	DATE
A4	MODIFY TORSION (1/A4)~(1/A4)	N1312010	Tom	Dec.12.2013
A3	ADD NOTE (1/A3)	N1308004	Tom	Aug.07.2013
A2	MODIFY VIEW (1/A2)~(3/A2)	ECN1308002	Tom	Aug.05.2013
A0	NEW RELEASE		Tom	Jun.14.2013

REVISIONS

DIM.	TOL.
X	±0.30
X.X	±0.25
X.XX	±0.20
X.XXX	±0.15
GENERAL ANGLE: ±3'	



TITLE:

D-SUB 15P FEMALE R/A DIP TYPE

DWG. NO.:

C-DB311CNAH2S1-15A-C2

DRAWN:

Tom

PART NO.:

DB311CNAH2S1-15A-C2

CHECKED:

Milo

UNIT:

mm

SCALE:

none

SHEET:

1 OF 1

DWG. SIZE:

A4

LAYER:

CPC

APPROVED:

Peter

RFQ NO.:

Q1303055-1

